ABSTRACT

TAPE HAVING IMPLANTABLE CONDUCTIVE LANDS FOR SEMICONDUCTOR PACKAGING PROCESS AND METHOD FOR MANUFACTURING THE SAME

A tape having implantable conductive lands, which realizes a new structure in which an organic rigid substrate is removed from a semiconductor package in a semiconductor packaging process, and a method for manufacturing the tape are provided. The tape includes a tape film, which can be detached from a semiconductor package after an encapsulation process and serves as a general rigid substrate until the encapsulation process is completed, and implantable conductive lands adhering to the tape film. The tape having the implantable conductive lands may be manufactured by laminating a foil for the implantable conductive lands on the tape film and performing photolithography, by printing the implantable conductive lands on the tape film, by attaching the implantable conductive lands that are individually made in advance on the tape film and performing lamination, by depositing and patterning a material layer for the implantable conductive lands on the tape film, or by forming seed layers on the tape film and performing electroplating.

FIG. 2